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International knowledge spillover through trade: A time-varying spatial panel data approach

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Highlights of " International Knowledge Spillover through Trade:

A Time-Varying Spatial Panel Data Approach"

by Chun-Yu Ho, Wei Wang and Jihai Yu

1. We examine international knowledge spillover through bilateral trade using a sample of 30 countries over the period 1975-2010.
2. We use a time-varying spatial panel data approach to incorporate the time-varying feature of trade flow.
3. We find that there is a positive spillover effect of innovation from one country to its trade partners through bilateral import flows.
4. The spillover effect accounts for approximately 1.3-3.6% of the total effect of R&D input on innovation output over time.

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